

FORMATION OF THIN FILM RESISTORS**Abstract of the Disclosure**

The invention is directed to thin film resistors which may be imbedded in multi-layer printed circuit boards. The invention is also directed to structures for forming such thin film resistors and to methods for forming such structures, including the use of combustion chemical vapor deposition. The invention is also directed to chemical precursor solutions by which resistive materials can be deposited on a substrate by combustion chemical vapor deposition techniques.

FIGURE 6